

HVD191

Silicon Epitaxial Planar PIN Diode for High Frequency Attenuator

REJ03G0015-0100Z
Rev.1.00
Apr.28.2003

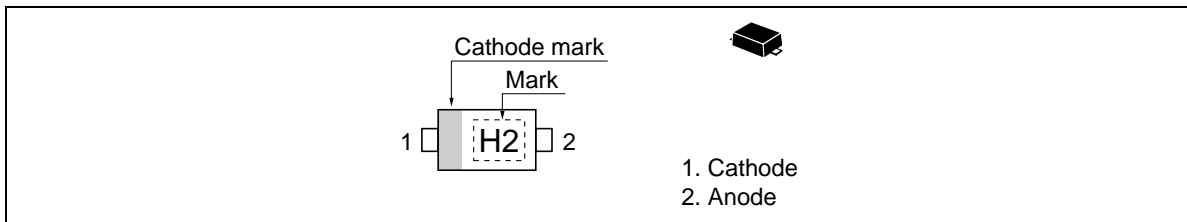
Features

- Low capacitance. ($C \leq 0.37$ pF)
- Low forward resistance. ($r_f \leq 2.5 \Omega$)
- Super small Flat Package (SFP) is suitable for surface mount design.

Ordering Information

| Type No. | Laser Mark | Package Code |
|----------|------------|--------------|
| HVD191 | H2 | SFP |

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

| Item | Symbol | Value | Unit |
|----------------------|----------------|-------------|------|
| Reverse voltage | V _R | 30 | V |
| Forward current | I _F | 100 | mA |
| Power dissipation | Pd | 150 | mW |
| Junction temperature | Tj | 125 | °C |
| Storage temperature | Tstg | -55 to +125 | °C |

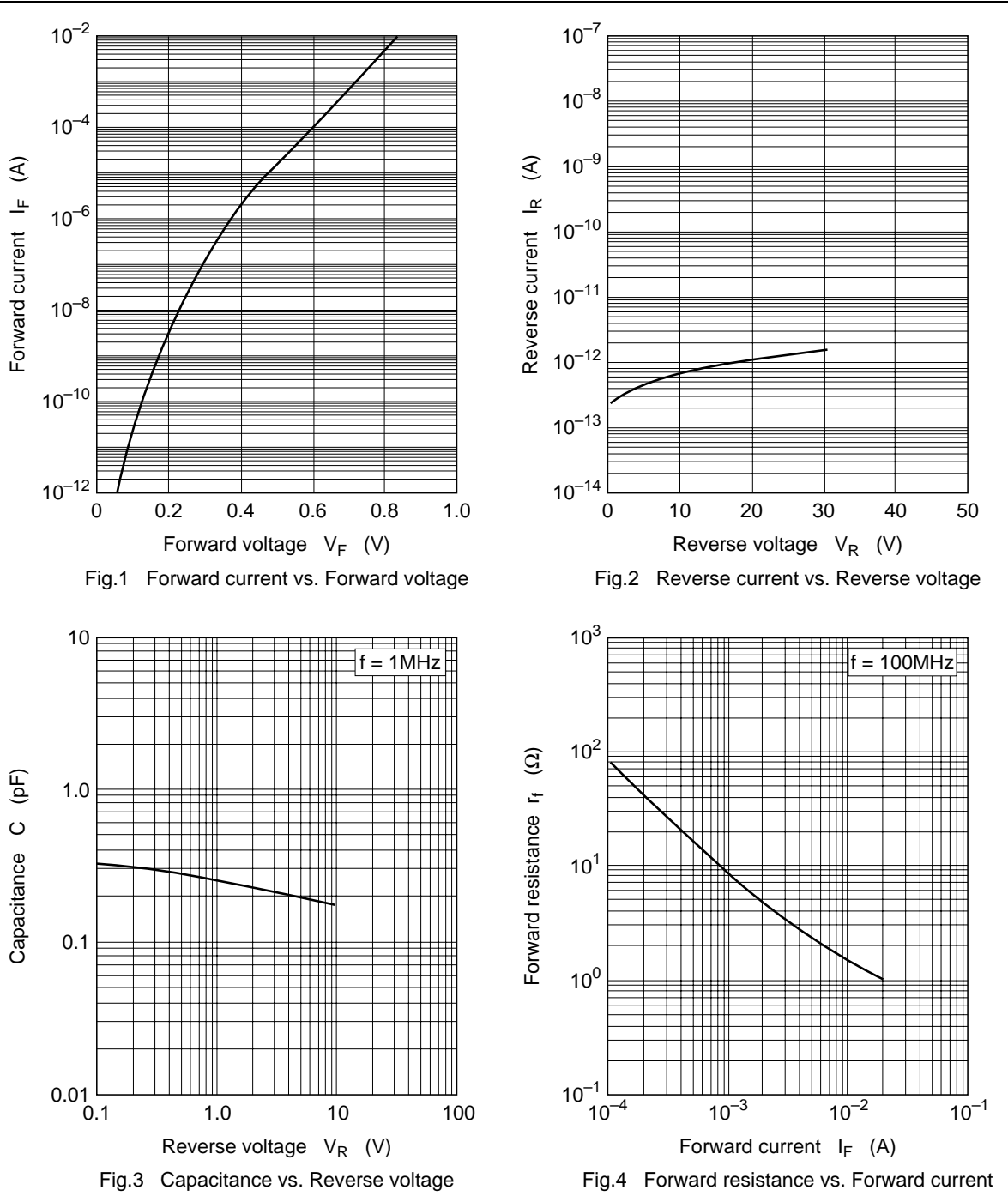
Electrical Characteristics

(Ta = 25°C)

| Item | Symbol | Min | Typ | Max | Unit | Test Condition |
|--------------------|----------------|-----|-----|------|------|-------------------------------------|
| Forward voltage | V _F | — | — | 1.0 | V | I _F = 10 mA |
| Reverse current | I _R | — | — | 0.1 | μA | V _R = 30 V |
| Capacitance | C | — | — | 0.37 | pF | V _R = 1 V, f = 1 MHz |
| Forward resistance | r _f | — | — | 2.5 | Ω | I _F = 10 mA, f = 100 MHz |

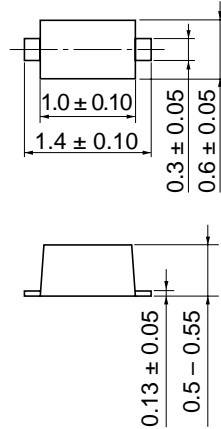
- Notes: 1. Please do not use the soldering iron due to avoid high stress to the SFP package.
2. The material of lead is exposed for cutting plane. Therefore, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic



Package Dimensions

As of January, 2003
Unit: mm



| | |
|------------------------|----------|
| Package Code | SFP |
| JEDEC | — |
| JEITA | — |
| Mass (reference value) | 0.0010 g |

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